

Description:

The SLR1117A is a low dropout, three terminals regulator designed to provide output current up to 1A. The device is available in an adjustable version and fixed output voltage of 1.8V, 2.5V and 3.3V. Dropout voltage of maximum of 1.5V is guaranteed at 1A output current. The quality of low dropout voltage and fast transient response make this device ideal for low voltage microprocessor applications. The SLR1117A requires output capacitance of a minimum of 10µF for stability. Built-in output current limiting and thermal limiting provide maximal protection to the SLR1117A against fault conditions.

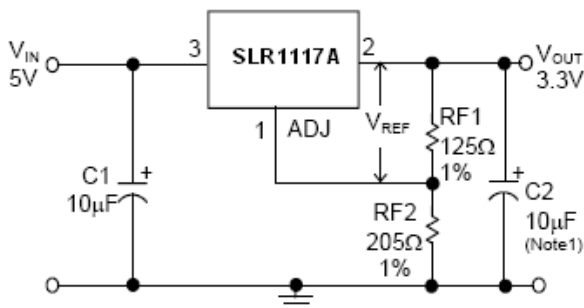
Features:

- Dropout Voltage 1.3V at 1A Output Current.
- Fast Transient Response.
- Line Regulation, typical at 0.015%.
- Load Regulation, typical at 0.1%.
- Current Limiting and Thermal Protection.
- Adjustable Output Voltage or Fixed 1.8V, 2.5V and 3.3V.
- Standard 3-Pin Power Packages.

Applications:

- Active SCSI Terminators.
- Post Regulators for Switching Supplies.
- Battery Chargers.
- PC Add-On Card.

Typical application circuit:



$$V_{REF} = V_{OUT} - V_{ADJ} = 1.25V \text{ (typ.)}$$

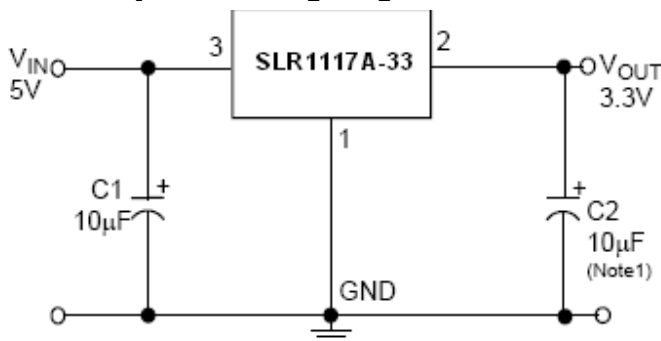
$$V_{OUT} = V_{REF} \times (1 + RF2/RF1) + I_{ADJ} \times RF2$$

$$I_{ADJ} = 55\mu A \text{ (typ.)}$$

(1) C1 needed if device is far away from filter capacitors.

(2) C2 required for stability.

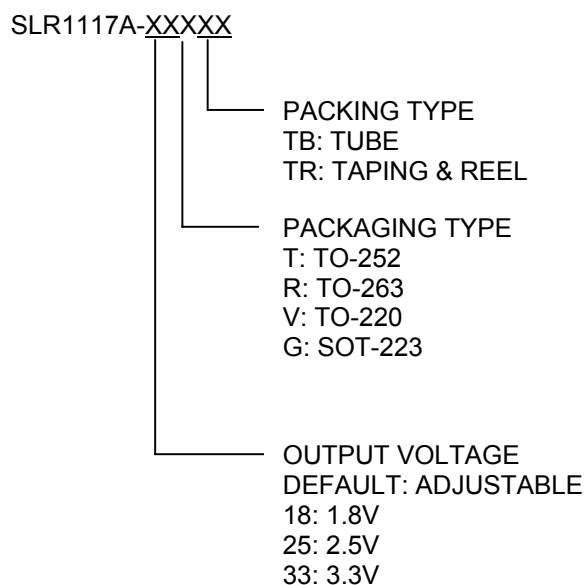
Adjustable Voltage Regulator



Fixed Voltage Regulator



Ordering Information:



Example: SLR1117A-25TTR
 → 2.5V version in TO-252 Green
 Package & Taping & Reel Packing Type
 Example: SLR1117A-25GTR
 → 2.5V version in SOT-223 Lead Free
 Package & Taping & Reel Packing Type

PIN CONFIGURATION	
TO-252 TOP VIEW 1: ADJ (GND) 2: VOUT (TAB) 3: VIN	
TO-263 TOP VIEW 1: ADJ (GND) 2: VOUT (TAB) 3: VIN	
TO-220 FRONT VIEW 1: ADJ (GND) 2: VOUT (TAB) 3: VIN	
SOT-223 FRONT VIEW 1: ADJ (GND) 2: VOUT (TAB) 3: VIN	

Marking Diagram:

Part No.	Marking
SLR1117A-18GTR	BS18G
SLR1117A-25GTR	BS25G
SLR1117A-33GTR	BS33G



Absolute Maximum Ratings:

VIN pin to ADJ/GND pin	7V
Operating Temperature Range	-40°C to 85°C
Maximum Junction Temperature	125°C
Storage Temperature Range	-65°C ~ 150°C
Lead Temperature (Soldering) 10 sec.	260°C
Thermal Resistance Junction to Case TO-252	12.5°C/W
TO-263, TO-220.....	3°C/W
SOT-223.....	15°C/W
Thermal Resistance Junction to Ambient TO-252	100°C/W
(Assume no ambient airflow, no heatsink) TO-263	60°C/W
SOT-223.....	155°C/W
TO-220.....	50°C/W

Absolute Maximum Ratings are those values beyond which the life of a device may be impaired.

Test Circuit

Refer to TYPICAL APPLICATION CIRCUIT.

Electrical Characteristics

(VIN=5V, TJ=25°C, IO=10mA, unless otherwise specified) (Note2)

PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Reference Voltage	TJ=25°C	1.238	1.25	1.262	V
	0°C≤TJ≤125°C 2.65V≤VIN≤7V 10mA≤IO≤1A	1.225	1.25	1.275	
Output Voltage	SLR1117A-18, VIN=3.3V	1.78	1.80	1.82	V
	SLR1117A-25, VIN=5V	2.47	2.50	2.53	
	SLR1117A-33, VIN=5V	3.26	3.30	3.33	
	SLR1117A 0°C≤TJ≤125°C 2.65V≤VIN≤7V 10mA≤IO≤1A	0.98VOUT	VOUT	1.02VOUT	



Electrical Characteristics (Continued)

PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Line Regulation	2.65≤V _{IN} ≤7V, T _J =25°C		0.015	0.2	%V _{OUT}
	0°C≤T _J ≤125°C		0.035	0.2	
Load Regulation	T _J =25°C, I _O =10mA ~1A		0.1	0.3	%V _{OUT}
	0°C≤T _J ≤125°C		0.2	0.4	
Dropout Voltage	ΔV _{OUT} , ΔV _{REF} =1%, I _O =1A		1.3	1.5	V
Current Limit		1			A
Adjusted Pin Current (I _{ADJ})	2.65≤V _{IN} ≤7V 10mA≤I _O ≤1A		55	120	μA
Adjusted Pin Current Change (ΔI _{ADJ})	2.65≤V _{IN} ≤7V 10mA≤I _O ≤1A		0.2	5	μA
Temperature Stability	I _O =0.5A 0°C≤T _J ≤125°C		0.5		% V _{OUT}
Minimum Load Current (Adj.)			5	10	mA
Quiescent Current (Fixed Version)			10	14	mA
RMS Output Noise (% of V _{OUT})	10Hz ≤ f ≤ 10KHz		0.003		%V _{OUT}
Ripple Rejection Ratio	120Hz input ripple C _{OUT} =25μF	60	72		dB

Note 1: To avoid output oscillation, aluminum electrolytic output capacitor is recommended and ceramic capacitor is not suggested.

Note 2: Specifications are production tested at T_A=25°C. Specifications over the -40°C to 85°C operating temperature range are assured by design, characterization and correlation with Statistical Quality Controls (SQC).

Typical Performance Characteristics

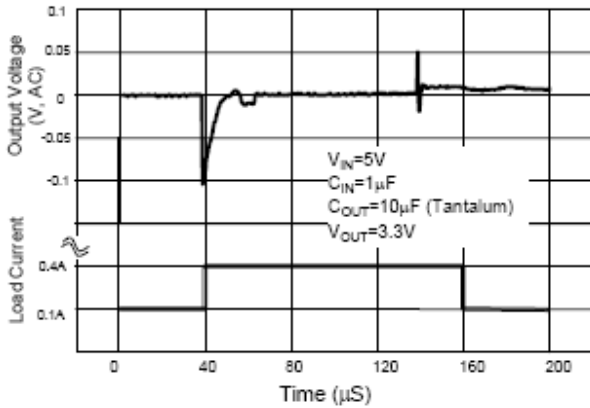


Fig. 1 Load Transient Response

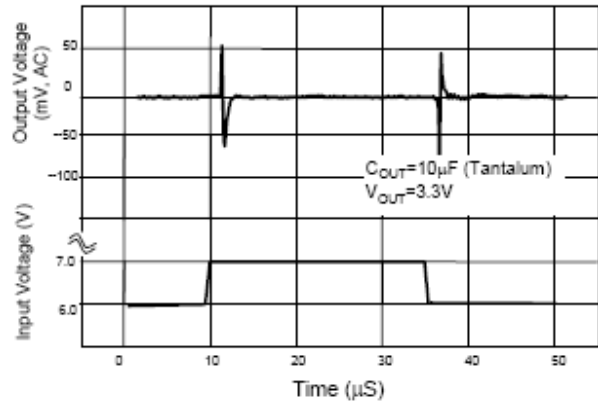


Fig. 2 Line Transient Response

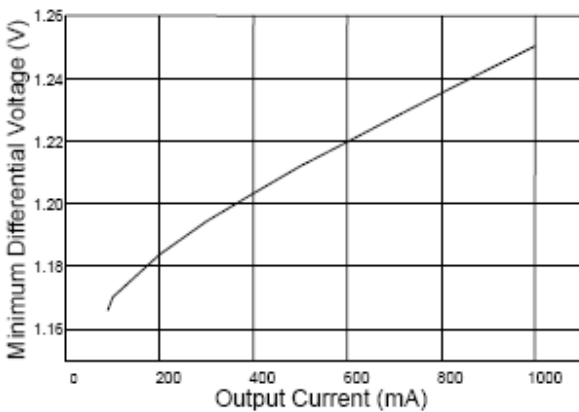


Fig. 3 Dropout Voltage ($V_{OUT}=3.3V$)

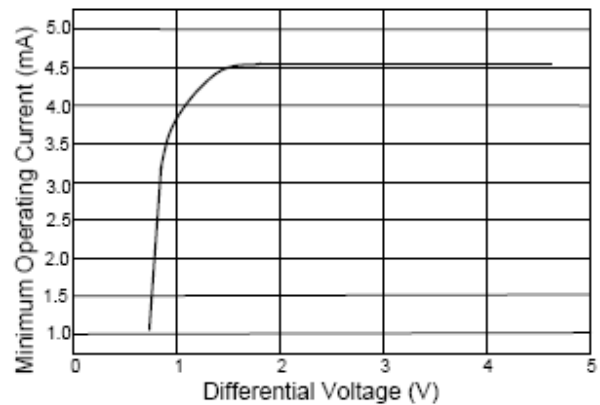


Fig. 4 Minimum Operating Current

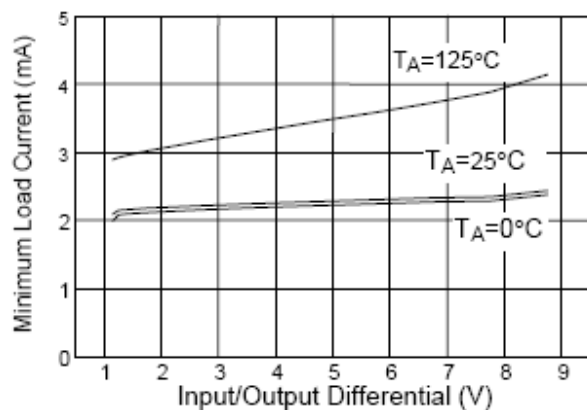
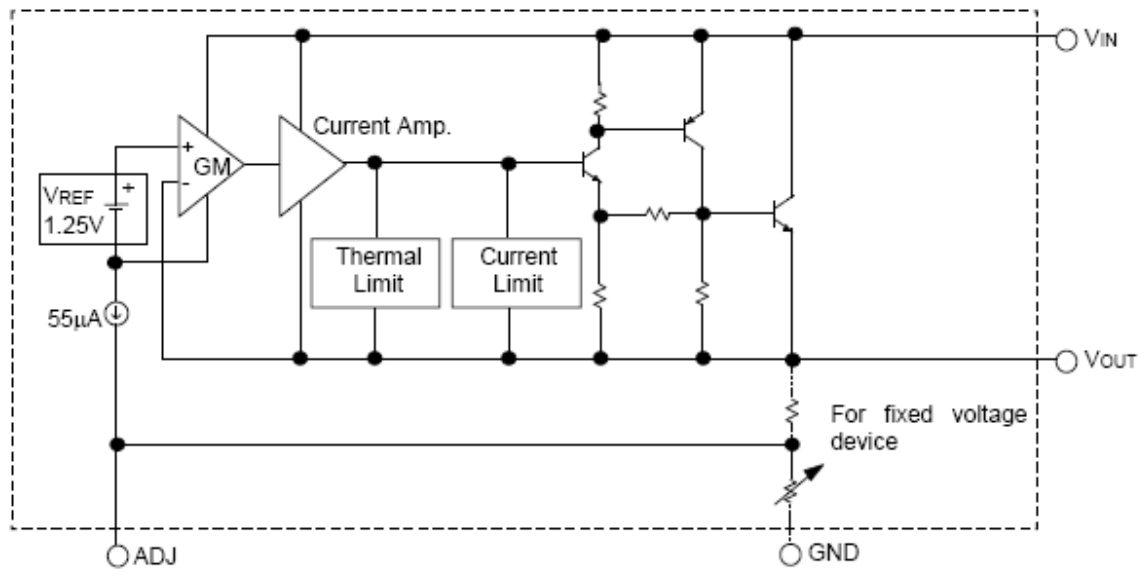


Fig. 5 Minimum Load Current (Adjustable Version)

Block Diagram



Pin Descriptions

- ADJ PIN - Providing $V_{REF} = 1.25V$ (typ.) for adjustable V_{OUT} . $V_{REF} = V_{OUT} - V_{ADJ}$ and $I_{ADJ} = 55\mu A$ (typ.)
(GND PIN- Power ground.)
- VOUT PIN - Adjustable output voltage.
- VIN PIN - Power Input.

Application Information

INPUT-OUTPUT CAPACITORS

Linear regulators require input and output capacitors to maintain stability. Input capacitor at 10µF with a 10µF aluminum electrolytic output capacitor is recommended.

POWER DISSIPATION

The SLR1117A obtains thermal-limiting circuitry, which is designed to protect the device against overload condition. For continuous load condition, maximum rating of junction temperature must not be exceeded. It is important to pay more attention in thermal resistance. It includes junction to case, junction to ambient. The maximum power dissipation of SLR1117A depends on the thermal resistance of its case and circuit board, the temperature difference between the die junction and ambient air, and the rate of airflow. The rate of temperature rise is greatly affected by the mounting pad configuration on the PCB, the board material, and the ambient temperature. When the IC mounting with good thermal conductivity is used, the junction temperature will be low even when large power dissipation applies.

The power dissipation across the device is $P = I_{OUT} (V_{IN} - V_{OUT})$.

The maximum power dissipation is:

$$P_{MAX} = \frac{(T_{J-max} - T_A)}{R_{\theta JA}}$$

Where T_{J-max} is the maximum allowable junction temperature (125°C), and T_A is the ambient temperature suitable in application.

As a general rule, the lower temperature is, the better reliability of the device is. So the PCB mounting pad should provide maximum thermal conductivity to maintain low device temperature.

Application Examples

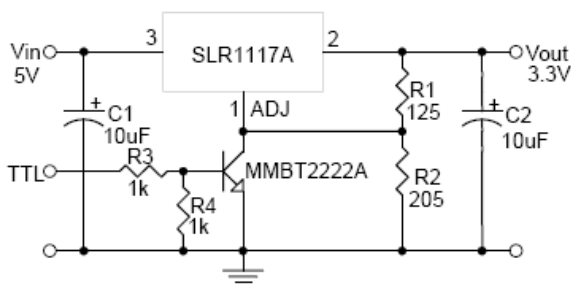
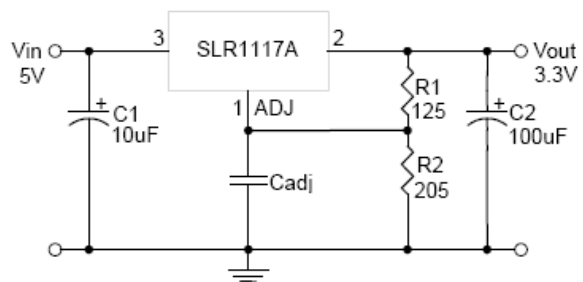


Fig. 6 V_{OUT}=3.3V with Shutdown



* Cadj can improve ripple rejection

Fig. 7 Improving Ripple Rejection

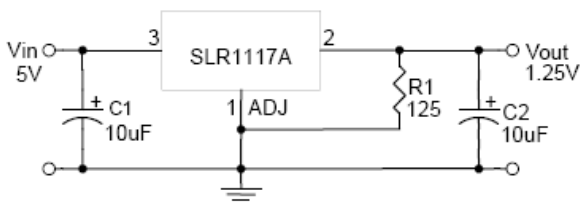


Fig. 8 V_{OUT}=1.25V Application Circuit

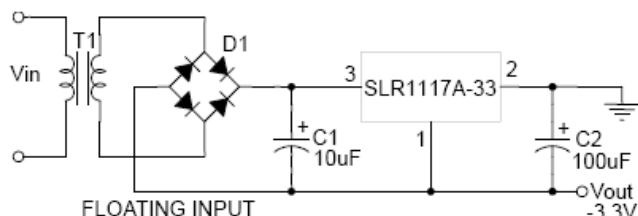
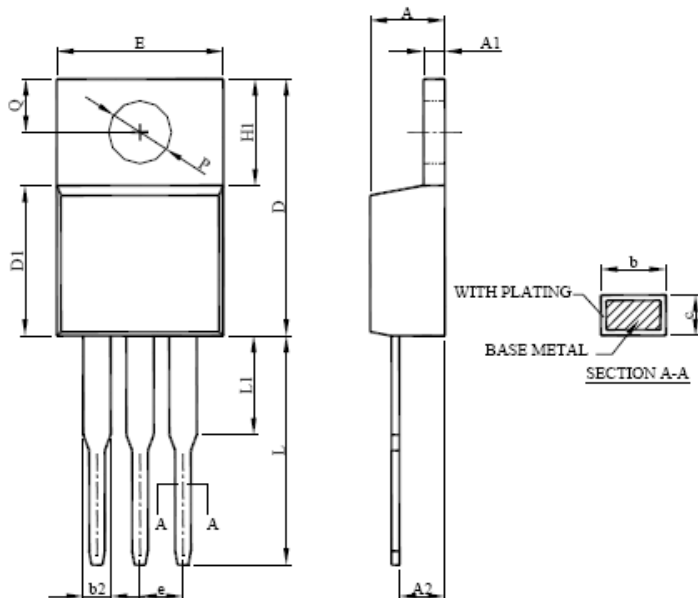


Fig. 9 Low Dropout Negative Supply

Physical Dimensions

TO-220 (unit: mm)

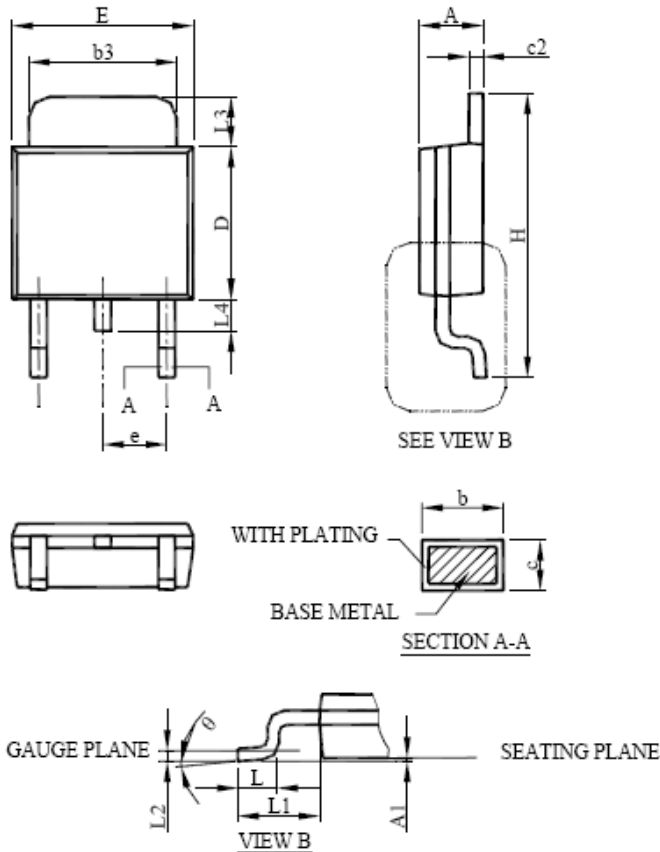


SYMBOL	TO-220	
	MILLIMETERS	
	MIN.	MAX.
A	3.56	4.82
A1	0.51	1.39
A2	2.04	2.92
b	0.38	1.01
b2	1.15	1.77
c	0.35	0.61
D	14.23	16.51
D1	8.38	9.02
E	9.66	10.66
e	2.54 BSC	
H1	5.85	6.85
L	12.70	14.73
L1	--	6.35
P	3.54	4.08
Q	2.54	3.42

Note:

1. Refer to JEDEC TO-220AB.
2. Dimension "E" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension "D1" does not include inter-lead flash or protrusions.
4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

TO-252 (unit: mm)

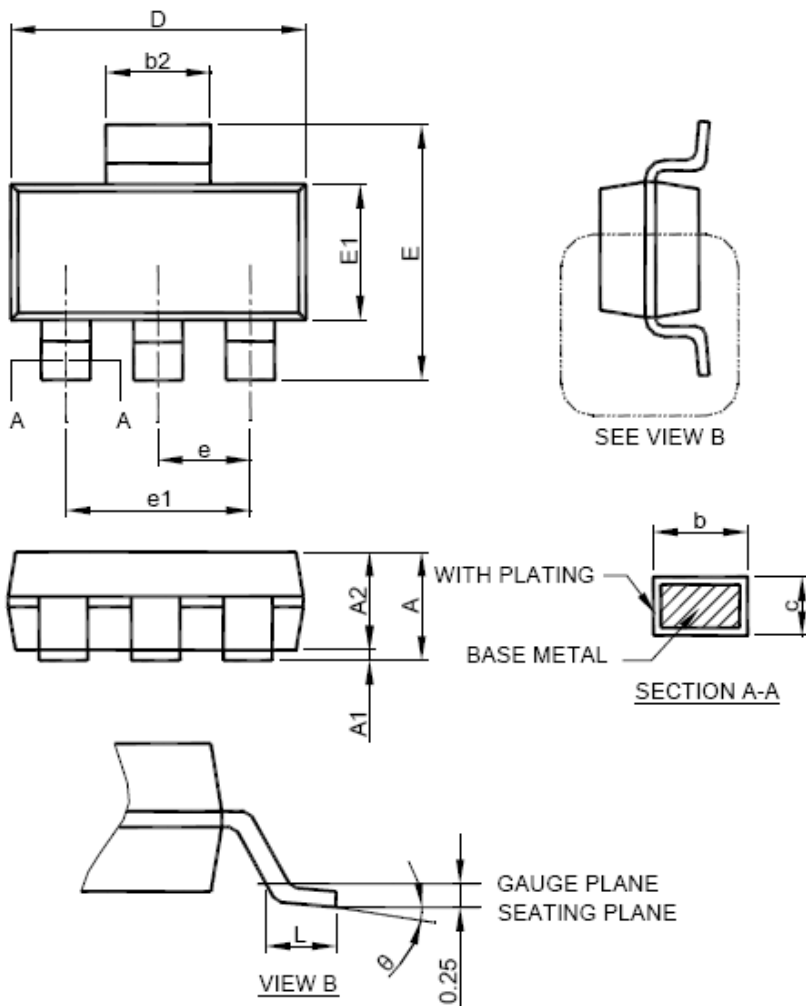


SYMBOL	TO-252-3L	
	MILLIMETERS	
	MIN.	MAX.
A	2.19	2.38
A1	0.00	0.13
b	0.64	0.89
b3	4.95	5.46
c	0.46	0.61
c2	0.46	0.89
D	5.33	6.22
E	6.35	6.73
e	2.28 BSC	
H	9.40	10.41
L	1.40	1.78
L1	2.67 REF	
L2	0.51 BSC	
L3	0.89	2.03
L4	--	1.02
θ	0°	8°

Note:

1. Refer to JEDEC TO-252AA and AB.
2. Dimension "E" do not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension "D" does not include inter-lead flash or protrusions.
4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

SOT-223(unit: mm)



SYMBOL	SOT-223	
	MILLIMETERS	
	MIN.	MAX.
A		1.80
A1	0.02	0.10
A2	1.55	1.65
b	0.66	0.84
b2	2.90	3.10
c	0.23	0.33
D	6.30	6.70
E	6.70	7.30
E1	3.30	3.70
e	2.30 BSC	
e1	4.60 BSC	
L	0.90	
θ	0°	8°

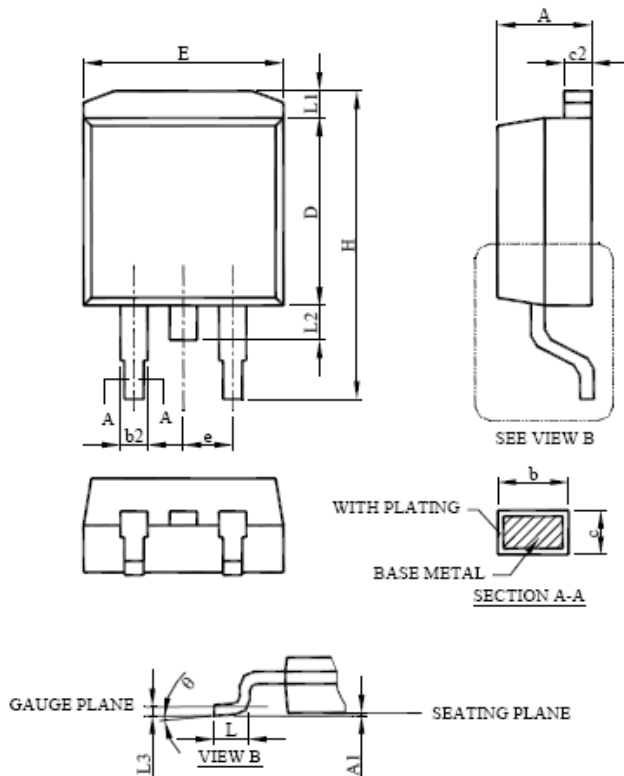
Note: 1. Refer to JEDEC TO-261AA.

2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side .

3. Dimension "E1" does not include inter-lead flash or protrusions.

4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

TO-263 (unit: mm)



SYMBOL	TO-263-3L	
	MILLIMETERS	
	MIN.	MAX.
A	4.06	4.83
A1	0.00	0.25
b	0.51	0.99
b2	1.14	1.78
c	0.38	0.74
c2	1.14	1.65
D	8.38	9.65
E	9.65	10.67
e	2.54 BSC	
H	14.61	15.88
L	1.78	2.79
L1	--	1.68
L2	--	1.78
L3	0.25 BSC	
θ	0°	8°

Note:

1. Refer to JEDEC TO-263AB.
2. Dimension "E" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side.
3. Dimension "D" does not include inter-lead flash or protrusions.
4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.



SLR1117A

Technical Data
Data Sheet N1576, Rev. -

800mA Low Dropout Positive Regulator

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